

AMENDMENTS TO THE CLAIMS

Please **CANCEL** claims 2, 3, 15, and 24 without prejudice or disclaimer.

Please **AMEND** claims 1, 10, 14, and 23 as shown below.

The following is a complete list of all claims in this application.

1. (Presently Amended) A poly amic acid precursor comprising at least one anhydride and at least one diamine in a cosolvent of tetrahydrofuran and N-methylpyrrolidinone, wherein said tetrahydrofuran is in an amount ranging from about 60% to about 90% by volume of tetrahydrofuran and N-methylpyrrolidinone.

2. (Presently Cancelled)

3. (Presently Cancelled)

4. (Original) The poly amic acid precursor of claim 1 wherein said at least one anhydride is a combination of 4,4'-oxydipthalic anhydride and 3,3',4,4'-biphenyltetracarboxylic dianhydride.

5. (Original) The poly amic acid precursor of claim 4 wherein the mole ratio of 3,3',4,4'-biphenyltetracarboxylic dianhydride to 4,4'-oxydipthalic anhydride ranges from about 25% to about 75% 3,3',4,4'-biphenyltetracarboxylic dianhydride.

6. (Original) The poly amic acid precursor of claim 4 wherein the mole ratio of 3,3',4,4'-biphenyltetracarboxylic dianhydride to 4,4'-oxydiphthalic anhydride is about 50% 3,3',4,4'-biphenyltetracarboxylic dianhydride.

7. (Original) The poly amic acid precursor of claim 1 wherein the diamine is 3,4'-oxydianiline.

8. (Original) The poly amic acid precursor of claim 1 further comprising at least 1 weight % of an inorganic filler selected from the group consisting of mica, silica, calcium carbonate, calcium phosphate, calcium silicate, talc, and a combination thereof.

9. (Original) A polyamic acid precursor comprising:
3,3' ,4,4'-biphenyltetracarboxylic dianhydride and 4,4'-oxydiphthalic anhydride in a molar ratio of about 50% 3,3' ,4,4'-biphenyltetracarboxylic dianhydride;
3,4'-oxydianiline in a molar ratio of about 50% 3,4'-oxydianiline to 3,3',4,4'-biphenyltetracarboxylic dianhydride and 4,4'-oxydiphthalic anhydride; and
a cosolvent comprising about 70% tetrahydrofuran and about 30% N-methylpyrrolidinone by volume of cosolvent.

10. (Presently Amended) A method for producing a polyimide comprising:
heating a poly amic acid precursor comprising at least one anhydride and at least one diamine in a cosolvent of tetrahydrofuran and N-methylpyrrolidinone, wherein said tetrahydrofuran is in an amount ranging from about ~~1%~~ 60% to about 90% by volume of

tetrahydrofuran and N-methylpyrrolidinone, whereby a portion of the cosolvent is removed and a polyimide is formed.

11. (Original) The method of claim 10 further comprising adding at least 1 weight % of an inorganic filler selected from the group consisting of mica, silica, calcium carbonate, calcium phosphate, calcium silicate, talc, and a combination thereof to said poly amic acid precursor.

12. (Original) The method of claim 10 wherein the at least one anhydride is 4,4'-oxydiphthalic anhydride and 3,3',4,4'-biphenyltetracarboxylic dianhydride and the mole ratio of 3,3',4,4'-biphenyltetracarboxylic dianhydride to 4,4'-oxydiphthalic anhydride ranges from about 25% to about 75% 3,3',4,4'-biphenyltetracarboxylic dianhydride.

13. (Original) The method of claim 10 wherein the diamine is 3,4'-oxydianiline.

14. (Presently Amended) A polyimide laminate comprising:
a polyimide layer; and
a metal foil, wherein said polyimide laminate is produced by casting a polyamic acid precursor comprising at least one diamine and at least one anhydride in a cosolvent of tetrahydrofuran and N-methylpyrrolidinone onto a surface of the metal foil, followed by heating the polyamic acid solution to form the polyimide layer, wherein said tetrahydrofuran is in an amount ranging from about 60% to about 90% by volume of tetrahydrofuran and N-methylpyrrolidinone.

15. (Presently Cancelled)
16. (Original) The polyimide laminate of claim 14 wherein said polyamic acid precursor further contains at least 1 weight % of an inorganic filler selected from the group consisting of mica, silica, calcium carbonate, calcium phosphate, calcium silicate, talc, and a combination thereof.
17. (Original) The polyimide laminate of claim 14 wherein the at least one anhydride comprises 4,4'-oxydiphthalic anhydride and 3,3',4,4'-biphenyltetracarboxylic dianhydride.
18. (Original) The polyimide laminate of claim 17 wherein the mole ratio of 3,3',4,4'-biphenyltetracarboxylic dianhydride to 4,4'-oxydiphthalic anhydride ranges from about 25% to about 75% 3,3',4,4'-biphenyltetracarboxylic dianhydride.
19. (Original) The polyimide laminate of claim 17 wherein the mole ratio of 3,3',4,4'-biphenyltetracarboxylic dianhydride to 4,4'-oxydiphthalic anhydride is about 50% 3,3',4,4'-biphenyltetracarboxylic dianhydride.
20. (Original) The polyimide laminate of claim 14 wherein the diamine is 3,4'-oxydianiline.

21. (Original) The polyimide laminate of claim 14 wherein the poly amic acid precursor is quantitatively pumped and fed through a slit die and cast onto a surface of a metal foil.

22. (Original) The polyimide laminate of claim 14 wherein the metal foil is copper.

23. (Presently Amended) A process for producing a polyimide laminate comprising the steps of:

adding a poly amic acid precursor onto a surface of a substrate, wherein the polyamic acid precursor comprises at least one diamine and at least one anhydride in a cosolvent of tetrahydrofuran and N-methylpyrrolidinone, wherein said tetrahydrofuran is in an amount ranging from about 1% 60% to about 90% by volume of tetrahydrofuran and N-methylpyrrolidinone; and

heating the poly amic acid precursor on the substrate to remove tetrahydrofuran and N-methylpyrrolidinone thereby forming a polyimide laminate.

24. (Presently Cancelled)

25. (Original) The process of claim 23 wherein the poly amic acid precursor contains about 90% tetrahydrofuran and about 10% N-methylpyrrolidinone.

26. (Original) The process of claim 23 wherein the step of heating the poly amic acid precursor solution removes at least about 75% of the solvent.